

0,635mm MICRO EDGE CARD MEC6-DV SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC6-DV

Insulator Material: Black LCP
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50µ" (1,27µm) Ni
Operating Temp Range: -55°C to +125°C
Insertion Depth: (4,22mm) .166" to (5,66mm) .223"
Current Rating: Testing Now!
Voltage Rating: Testing Now!
RoHS Compliant: Yes



Processing:

Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x
Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0,10mm) .004" max (10-50) (0,15mm) .006" max (60-70)

Mates with: (1,60mm) .062" thick cards

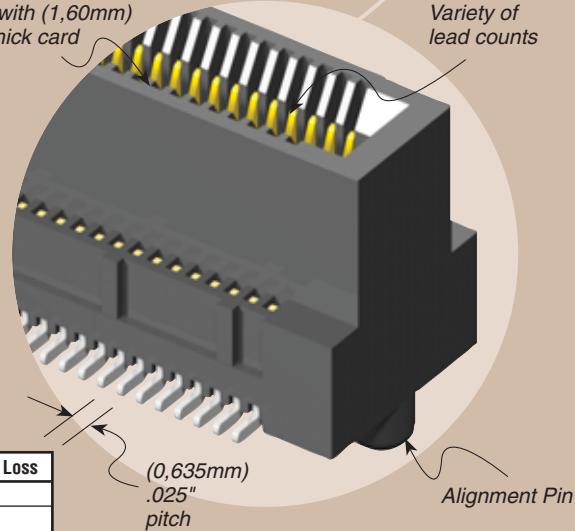
APPLICATION SPECIFIC OPTION

- Locking Clip
Call Samtec.

0,635mm MEC6-DV	Rated @ -3dB Insertion Loss
8,65mm Stack Height	
Single-Ended Signaling	7.5 GHz / 15 Gbps
Differential Pair Signaling	7.0 GHz / 14 Gbps

Mates with (1,60mm) .062" thick card

Variety of lead counts



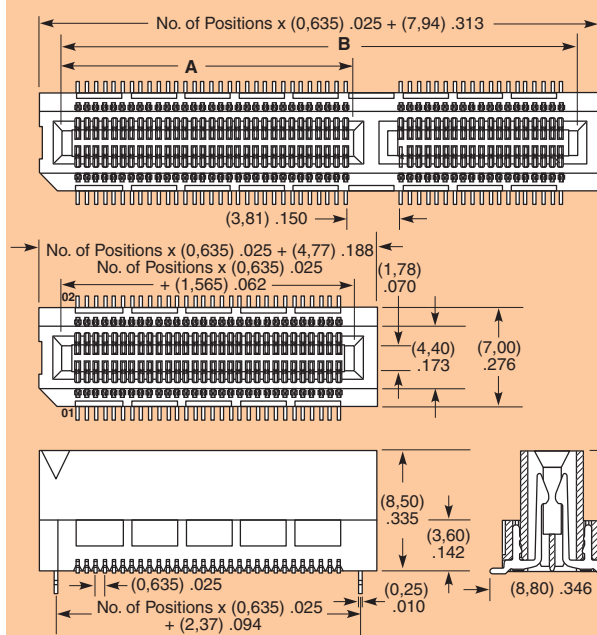
10, 20, 30, 40, 50, 60, 70

-S
= 30µ" (0,76µm) Gold on contact, Matte Tin on tail

-L
= 10µ" (0,25µm) Gold on contact, Matte Tin on tail

-K
= (5,50) .217" DIA Polyimide Pick & Place Pad

-TR
= Tape & Reel



POSITIONS PER ROW	A	B
50	(22,96) .904	(36,49) 1.437
60	(24,87) .979	(42,84) 1.687
70	(28,68) 1.129	(49,19) 1.937

Note: Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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